

**METHODS AND APPARATUS FOR WIRE BONDING WITH
WIRE LENGTH ADJUSTMENT IN AN INTEGRATED CIRCUIT**

Abstract

An integrated circuit is wire bonded in a manner such that there is consistent RF performance
5 from integrated circuit package to integrated circuit package. Bond distances within the integrated
circuit are measured, each corresponding to a wire bond to be formed. An area under a hypothetical
wire bond profile is calculated as a function of the bond distances, a baseline wire length, and a
baseline loop height. A wire is bonded across a given one of the bond distances to form a given one
of the wire bonds. A wire bond profile for the given wire bond is provided having an area thereunder
10 that is substantially equal to the calculated area.